



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-09
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS30L60CT	HFDZ*Z02Q02U	A	998G	2017-01-09
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	TO 220 AB NON ISOL			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 5th August 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product
Nickel	5.92	Leadframe	3115
Lead	12.01	Soft solder	6319

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HFDZ*20ZQ02U					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	14.452	mg	supplier	die	Silicon (Si)	7440-21-3		13.746	mg	951149	7235
				supplier	metallization	Aluminium (Al)	7429-90-5		0.569	mg	39372	299
				supplier	metallization	Titanium (Ti)	7440-32-6		0.013	mg	900	7
				supplier	metallization	Tungsten (W)	7440-33-7		0.020	mg	1384	11
				supplier	Passivation	Silicon Oxide	7631-86-9		0.084	mg	5811	44
Leadframe	Copper & its alloys	1258.924	mg	supplier	back side metallization	Gold (Au)	7440-57-5		0.020	mg	1384	11
				supplier	alloy	Copper (Cu)	7440-50-8		1251.376	mg	994004	658619
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	995	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	299	198
				supplier	metallization	Nickel (Ni)	7440-02-0		5.919	mg	4702	3115
Soft solder	Solder	12.573	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	12.007	mg	954983	6319
				supplier	solder	Silver (Ag)	7440-22-4		0.314	mg	24974	165
				supplier	solder	Tin (Sn)	7440-31-5		0.252	mg	20043	133
Bonding wires	Other inorganic materials	4.706	mg	supplier	wire	Aluminium (Al)	7429-90-5		4.706	mg	1000000	2477
Encapsulation	Other Organic Materials	602.983	mg	supplier	mold compound	Silica, vitreous	60676-86-0		524.595	mg	870000	276103
				supplier	mold compound	Epoxy resin	25068-38-6		60.298	mg	100000	31736
				supplier	mold compound	Phenol resin	29690-82-2		15.075	mg	25000	7934
				supplier	mold compound	Carbon Black	1333-86-4		3.015	mg	5000	1587
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348